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Applicants: Perez, Erasmo; Roman, David T.
Assignee: Amkor Technology, Inc.
Title: Semiconductor Package With Exposed Die Pad And Body-Locking Leadframe
Serial No.: 09/436,158 Filing Date: November 9, 1999
Examiner: N. Ha Group Art Unit: 2814
Docket No.: M-7744 US

San Jose, California
October 8, 2001

COMMISSIONER FOR PATENTS
Washington, D.C. 20231

**INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR § 1.97(c) WITH FEE**

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, § 1.97 and § 1.98, Applicants wish to call the documents listed on the accompanying PTO Form-1449 to the Examiner's attention. Copies of these documents are enclosed.

Citation of these documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, or
3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

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Statement fee under 37 C.F.R. § 1.17(p). The Commissioner is hereby authorized to charge

any additional fees which may be required, or credit any overpayment to Deposit Account

No. 19-2386. This paper is being submitted in duplicate.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to Commissioner for Patents, Washington, D.C. 20231, on October 8, 2001.

JEP

Attorney for Applicants

10/8/01

Date of Signature

Respectfully submitted,

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